

Appl. No. 09/876,290  
Amdt. Dated January 21, 2009  
Reply to Office Action of July 21, 2008

### REMARKS

Applicants have submitted this Request for Continued to Examination so that the Examiner may consider the alternate claims as modified herein. Specifically, by this amendment, Applicants have endeavored to eliminate the claim language to which the Examiner has raised objection. Applicants note that the referenced language is either redundant and or merely provides a functional description of the inherent properties of the structure as now claimed. Accordingly, Applicants have eliminated this language and therefore respectfully request that the Examiner withdraw the objections to the drawings and the rejections of the claims under 35 U.S.C. § 112, first paragraph. Applicant respectfully submits that the modified claims fully comport with the requirements of section 112.

In regard to the rejections set forth by the Examiner under 35 U.S.C. § 112, second para., Applicants have eliminated the references to the "base member". Accordingly, Applicants request that the Examiner withdraw the rejection set forth under 35 U.S.C. § 112, second paragraph.

Applicants respectfully request reconsideration of the prior art rejections set forth by the Examiner under 35 U.S.C. sections 102 and 103. Applicants respectfully submit that the prior art reference of record, whether considered alone, or in combination, fail to either teach or suggest Applicants' presently claimed invention. More specifically, by this amendment, Applicants have clarified the subject matter of the invention by specifying that the assembly jig is comprised of at least two side walls having a spacing that is only slightly larger than the semiconductor modules. The modules therefore have their respective positions restricted by the sidewalls so that a solder reflow operation may be performed to

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properly secure the plurality of solder modules located within the assembly in a desired arrangement. Applicants further note that this process also provides electrical communication between adjacent ones of the plurality of semiconductor modules.

In order to further highlight the distinctions between the present invention in the prior art, Applicants have also further modified each of the independent claims to specify that:

the plurality of semiconductor modules secured within the jig each being comprised of one or more semiconductor chips each secured to a printed wiring board that has electrical contacts at a top and bottom surface thereof and solder located between conductive pads on adjacent printed wiring boards and wherein adjacent semiconductor modules are secured to one another by solder connections between respective top and bottom surfaces thereof.

Applicants respectfully submit that none of the references cited by the Examiner teach or suggest this unique and advantageous structure. In contrast with the presently claimed invention, the primary Normington reference teaches that there should be an intervening structure between the printed wiring board modules of this reference. Furthermore, the Normington reference actually teaches away from the present invention by indicating that the side walls of the structures cited by the Examiner should be separated from the wiring board structure by wire bond leads that wrap around an outer perimeter thereof. It is only Applicants instant application which describes securing semiconductor modules within an assembly jig such that solder provides the only physical and electrical connection between adjacent semiconductor modules.

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Accordingly, in light of the foregoing, Applicants respectfully submit that all claims  
now standing condition for allowance.

Respectfully submitted,

Date:

1/21/09



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